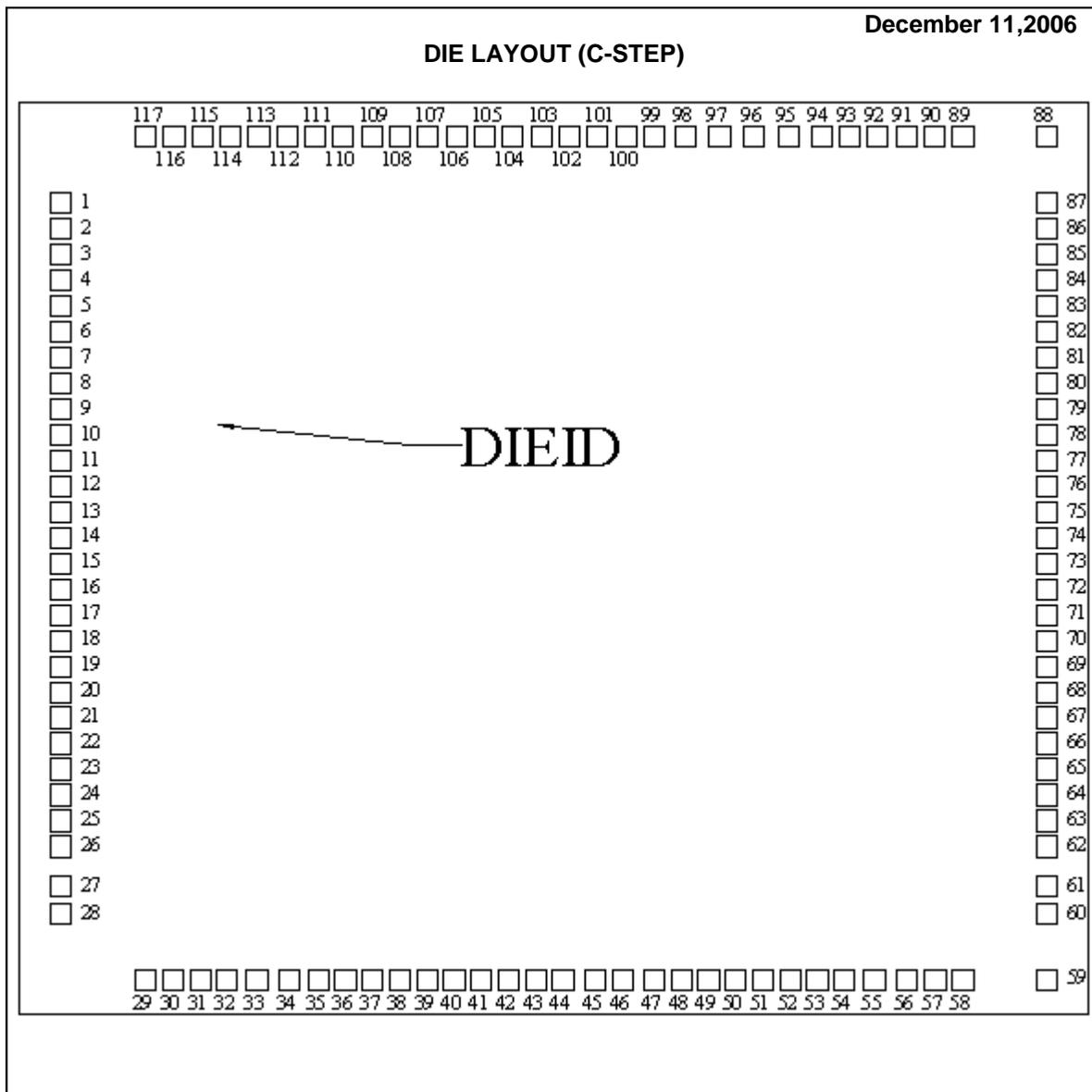


DS90C387 MDC MWC
DUAL PIXEL LVDS DISPLAY INTERFACE (LDI)-SVGA/QXGA



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	DS90C387C	Bond Pad Opening Size (min)	71µm x 71µm
Die Step	C	Bond Pad Metalization	0.5% COPPER_SINGLEL PLOY_DLM
Physical Attributes		Passivation	NITRIDE
Wafer Diameter	200mm	Back Side Metal	BARE BACK
Die Size (Drawn)	3381µm x 3969µm 133.1mils x 156.3mils	Back Side Connection	Floating
Thickness	254µm Nominal		
Min Pitch	95.5µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (C-Step)

(Referenced to die center, coordinates in μm) **NC** = No Connection, **N.U.** = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES		PAD SIZE	
		X	Y	X	Y
G11	1	-1826	1317	77	x 77
G10	2	-1826	1222	77	x 77
R17	3	-1826	1126	77	x 77
R16	4	-1826	1031	77	x 77
R15	5	-1826	935	77	x 77
R14	6	-1826	840	77	x 77
R13	7	-1826	745	77	x 77
R12	8	-1826	649	77	x 77
R11	9	-1826	554	77	x 77
R10	10	-1826	458	77	x 77
CLKIN	11	-1826	363	77	x 77
PLL _{VCC}	12	-1826	268	77	x 77
GND	13	-1826	172	77	x 77
GND	14	-1826	77	77	x 77
PRE	15	-1826	-19	77	x 77
PLLSEL	16	-1826	-114	77	x 77
PLLGND	17	-1826	-209	77	x 77
PLLGND	18	-1826	-305	77	x 77
PLL _{VCC}	19	-1826	-400	77	x 77
PLL _{VCC}	20	-1826	-496	77	x 77
PLLGND	21	-1826	-591	77	x 77
R_FB	22	-1826	-686	77	x 77
R_FDE	23	-1826	-782	77	x 77
/PD	24	-1826	-877	77	x 77
DUAL	25	-1826	-973	77	x 77
BAL	26	-1826	-1068	77	x 77
LVDSGND	27	-1826	-1215	77	x 77
LVDSGND	28	-1826	-1316	77	x 77
CLK2P/NC	29	-1513	-1561	77	x 77
CLK2M/NC	30	-1412	-1561	77	x 77
A7P	31	-1311	-1561	77	x 77
A7M	32	-1211	-1561	77	x 77
LVDSV _{CC}	33	-1101	-1561	77	x 77
LVDSV _{CC}	34	-982	-1561	77	x 77
A6P	35	-874	-1561	77	x 77
A6M	36	-773	-1561	77	x 77
A5P	37	-672	-1561	77	x 77
A5M	38	-572	-1561	77	x 77
LVDSGND	39	-471	-1561	77	x 77
LVDSGND	40	-370	-1561	77	x 77
A4P	41	-269	-1561	77	x 77
A4M	42	-168	-1561	77	x 77
A3P	43	-68	-1561	77	x 77
A3M	44	33	-1561	77	x 77
LVDSV _{CC}	45	150	-1561	77	x 77
LVDSV _{CC}	46	255	-1561	77	x 77
CLK1P	47	370	-1561	77	x 77
CLK1M	48	471	-1561	77	x 77
LVDSGND	49	572	-1561	77	x 77
LVDSGND	50	672	-1561	77	x 77

A2P	51	773	-1561	77	x	77
A2M	52	874	-1561	77	x	77
A1P	53	975	-1561	77	x	77
A1M	54	1075	-1561	77	x	77
LVDSV _{CC}	55	1185	-1561	77	x	77
LVDSV _{CC}	56	1304	-1561	77	x	77
A0P	57	1412	-1561	77	x	77
A0M	58	1513	-1561	77	x	77
NC	59	1826	-1561	77	x	77
LVDSGND	60	1826	-1316	77	x	77
LVDSGND	61	1826	-1215	77	x	77
GND	62	1826	-1068	77	x	77
GND	63	1826	-973	77	x	77
V _{CC}	64	1826	-877	77	x	77
Hsync	65	1826	-782	77	x	77
Vsync	66	1826	-686	77	x	77
DE	67	1826	-591	77	x	77
B27	68	1826	-496	77	x	77
B26	69	1826	-400	77	x	77
B25	70	1826	-305	77	x	77
B24	71	1826	-209	77	x	77
B23	72	1826	-114	77	x	77
B22	73	1826	-19	77	x	77
B21	74	1826	77	77	x	77
B20	75	1826	172	77	x	77
G27	76	1826	268	77	x	77
G26	77	1826	363	77	x	77
V _{CC}	78	1826	458	77	x	77
GND	79	1826	554	77	x	77
GND	80	1826	649	77	x	77
G25	81	1826	745	77	x	77
G24	82	1826	840	77	x	77
G23	83	1826	935	77	x	77
G22	84	1826	1031	77	x	77
G21	85	1826	1126	77	x	77
G20	86	1826	1222	77	x	77
R27	87	1826	1317	77	x	77
NC	88	1826	1561	77	x	77
R26	89	1513	1561	77	x	77
R25	90	1407	1561	77	x	77
R24	91	1303	1561	77	x	77
R23	92	1198	1561	77	x	77
R22	93	1093	1561	77	x	77
R21	94	989	1561	77	x	77
V _{CC}	95	870	1561	77	x	77
V _{CC}	96	741	1561	77	x	77
GND	97	613	1561	77	x	77
GND	98	487	1561	77	x	77
R20	99	370	1561	77	x	77
B17	100	266	1561	77	x	77

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